

ABSTRACT

5 A method for fabricating an integrated circuit using a photo-lithographic
process includes the steps of placing at least two anti-reflective coating layers
between a reflective surface and another material. The indices of refraction,
absorptions, and thicknesses of the at least two anti-reflective coating layers are
chosen such that the amplitudes and phase differences of radiation reflected from the
10 anti-reflective coating layers, as well as any other reflective surfaces below the anti-
reflective coating layers, mutually cancel when combined. The invention may be
practiced using more than two layers of anti-reflective coating. Multiple layers of
anti-reflective coating may be used below an inter-level dielectric, in which case they
may serve the additional purpose of functioning as an etch-stop.

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